

# Multilayer Ceramic Chip Capacitors

### C3225X6S1V106K250AC









#### TDK item description C3225X6S1V106KT\*\*\*\*

Applications	Commercial Grade
Feature	General General (Up to 50V)
Series	C3225 [EIA 1210]
Status	Production



	Size	
Length(L)	3.20mm ±0.40mm	
Width(W)	2.50mm ±0.30mm	
Thickness(T)	2.50mm ±0.30mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	2.00mm to 2.40mm	
Recommended Land Pattern (PB)	1.00mm to 1.20mm	
Recommended Land Pattern (PC)	1.90mm to 2.50mm	

Electrical Characteristics		
Capacitance	10μF ±10%	
Rated Voltage	35VDC	
Temperature Characteristic	X6S(±22%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	50ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000pcs

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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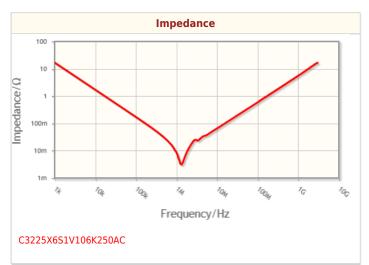


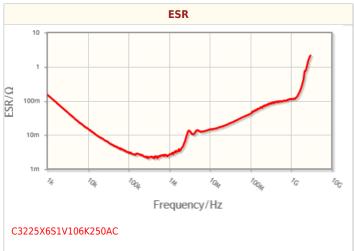


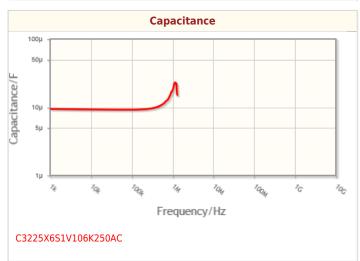


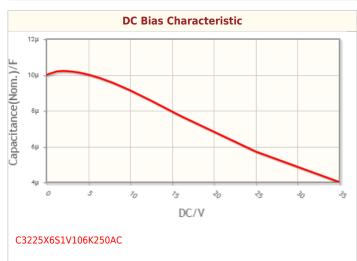


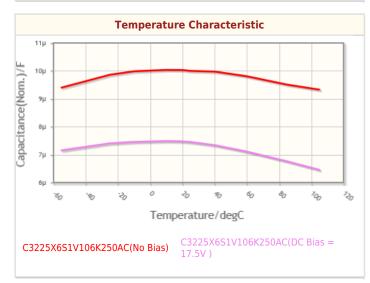
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

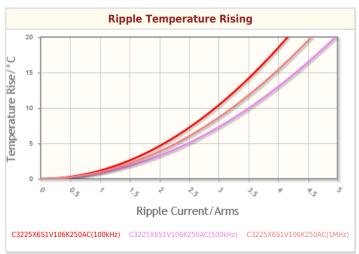












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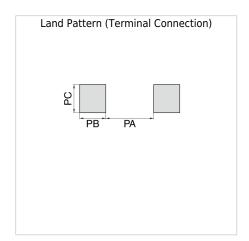








# **Associated Images**



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